

UT data analysis steps for development of automated detection technique of bonding defects in multi-layered structures

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Abstract: Multi-layered structures of adhesively bonded similar and dissimilar materials have a high interest in aerospace and automotive industries. Adhesive joining is more advanced technology which allows to join different types of materials, provide uniform load distribution and resistance to corrosion. Adhesive joining and composite materials are the key technology and materials which provide lightening of the structure as well as reduce CO2 emission. Adhesively bonded similar and dissimilar materials are usually used in secondary load carriers due to their advanced mechanical characteristics. However, this structures are still limited in use due to the absence of reliable method suitable for investigation of multi-layered structures and, especially, dissimilar material joints. It is problematic to detect bonding defects in multi-layered structures without complex modelling of sound propagation performed by numerical methods. This factor limits practical application of the technique.

Ultrasonic testing (UT) is the widely used non-destructive method for inspection of different materials and structures. A lot of research has been carried out to evaluate adhesion quality using ultrasonic inspection. This technique is one of the most suitable techniques for investigation of multi-layered structures. However, complex modelling of wave propagation is almost always required for the detection of bonding defects due to uncertainty factors such as inspection execution, component geometry, surface preparation, thickness of adhesive and adherents and signal reverberation which influence on the detection of interface defects. Therefore, the complex modelling and numerical evaluations can be eliminated by developing a robust method for automatic analysis of ultrasonic NDT data for detection of bonding defects in multi-layered structures. As a result, the objective of this work is to create steps of analysis of UT data for development of automated defect detection technique.

The experimental investigation of adhesively bonded materials was performed using ultrasonic inspection. The collected data was analyzed. Influential factors which have an impact on the interface defect detection were determined. The valuable features which are capable to increase probability of interface defect detection and features related to the defects for development of data post-processing technique were determined and extracted. The basic steps of analysis and algorithm of automated detection of interface defects are provided in this work. The reliability of the technique was evaluated and detected defects were sized.

Key words: data post-processing, automatic analysis, ultrasonic, adhesive joints, interface defects



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UT Data Analysis Steps For Development of Automated Detection Technique of Bonding Defects in Multi-layered Structures

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ORGANISERS



Relevance

- Development trends and main demands in automotive and aerospace industry is reduction of fuel consumption and carbon dioxide emission. In addition, adhesive bonding technique lightens the weight of entire structure.
- Multilayered structures bonded adhesively has improved performance:
 - Even distribution of mechanical strength;
 - Superior characteristics of fatigue life, impact resistance and residual strength.
- Reliable method for detection of defects in such structures should be developed to ensure life, health and environmental safety.

Problem

- Requirement of complex modeling of wave propagation for the detection of bonding defects;
- Related to samples:
 - multilayered structure
 - complex geometry
 - quite different elastic and acoustic properties of dissimilar materials
 - thin thickness of components
 - surface preparation.

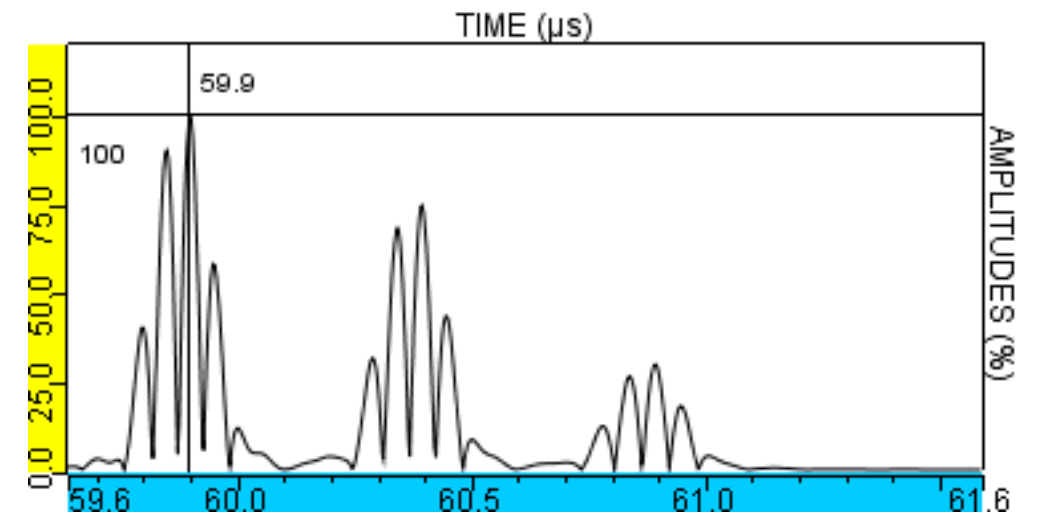
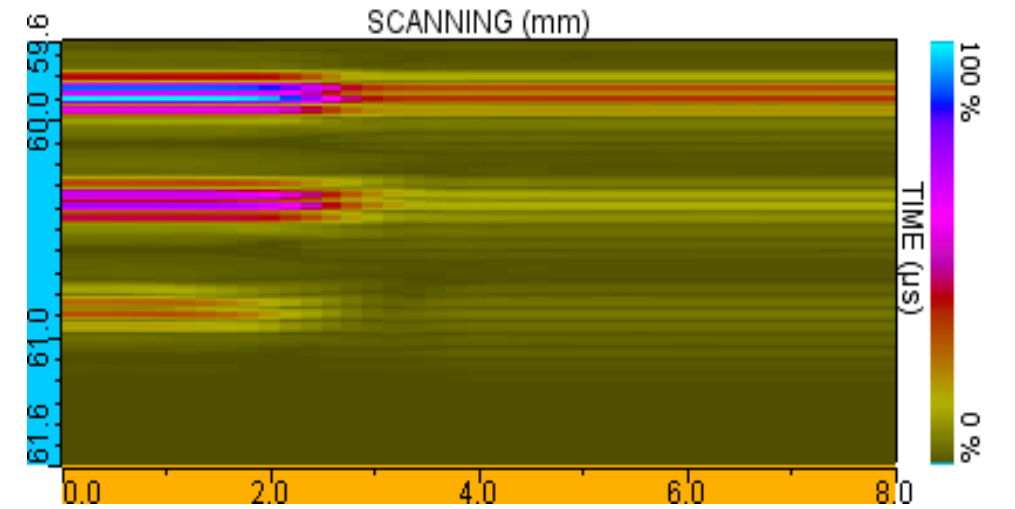
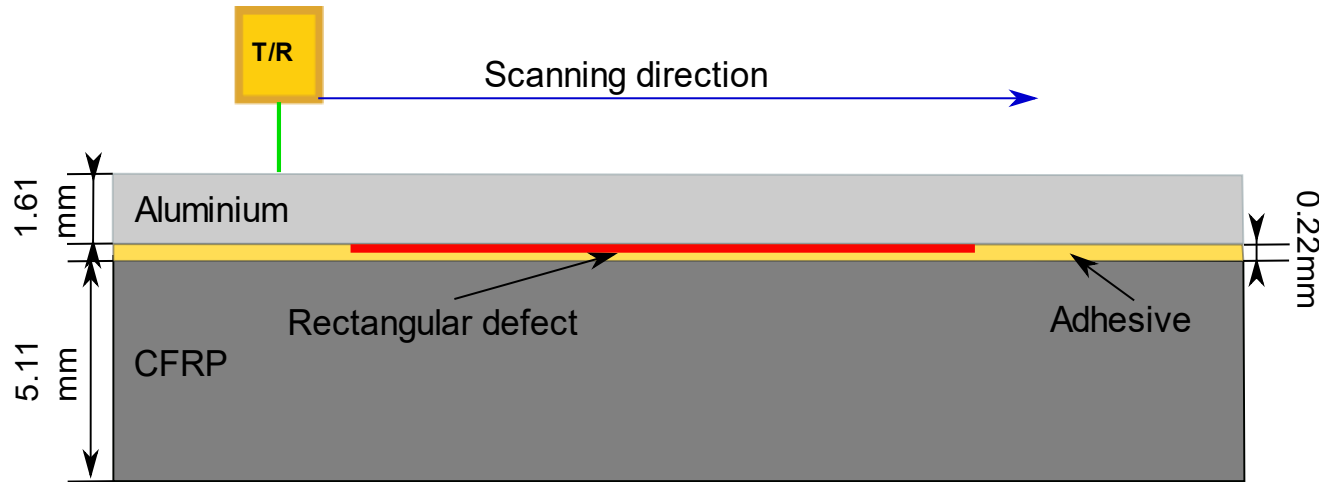
Objective & Tasks

- The objective of this work is to create steps of analysis of UT data for development of automated defect detection technique.
- Tasks:
 1. Development of the technique to eliminate influential factors affecting probability of bonding defects detection
 2. Determination & extraction of UT features capable to increase probability of defect detection
 3. Evaluation of extracted features performance using -6dB threshold sizing method

Task 1: Development of the technique to eliminate influential factors affecting probability of bonding defects detection

Determination of Influential Factors: Sensitivity Analysis

- Calibration



Determination of Influential Factors: Sensitivity Analysis

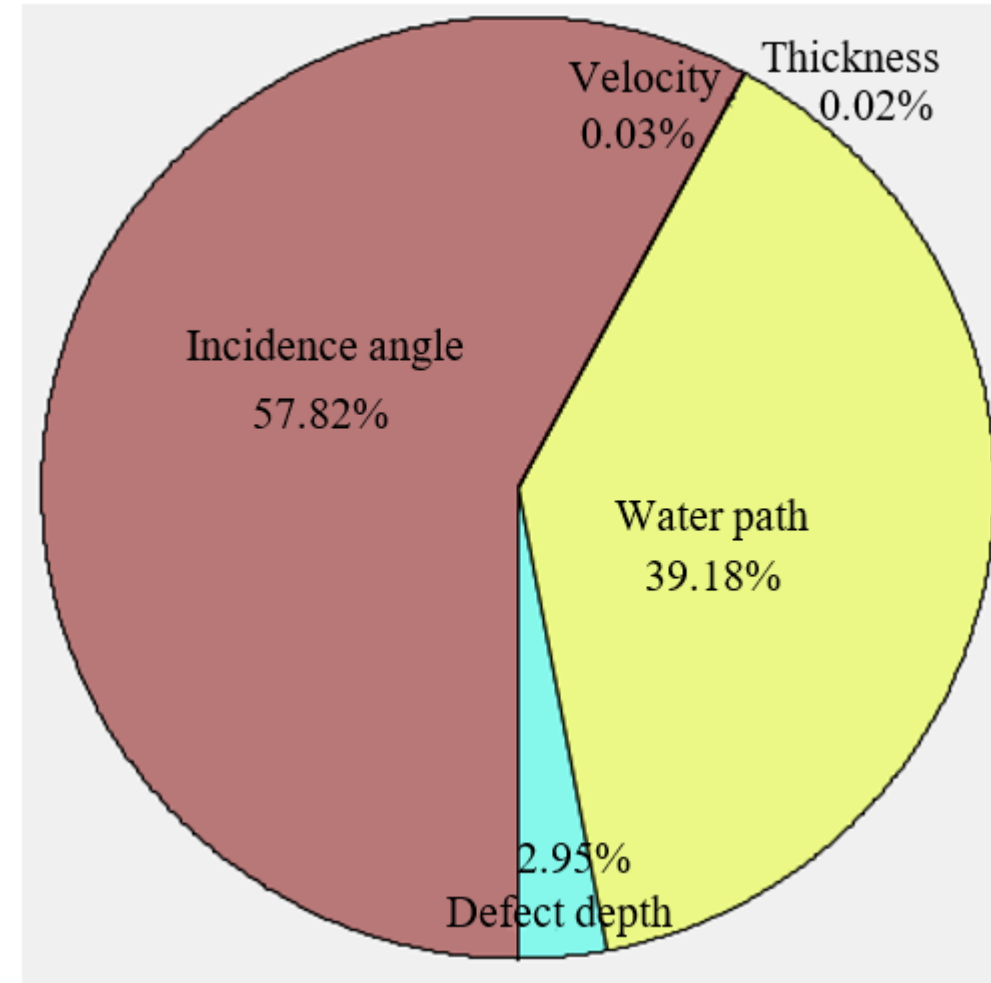
- Metamodel computation

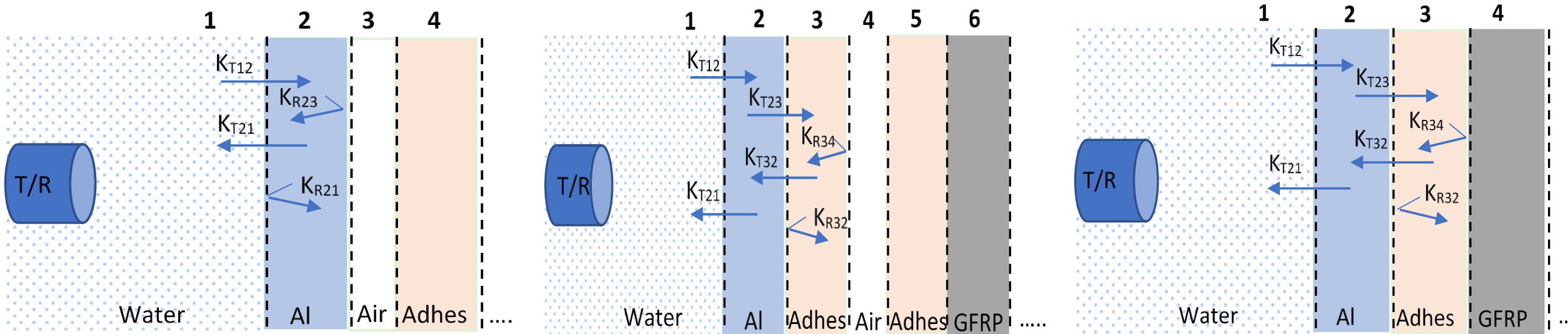
Parameters	Mean value	Variation range	Statistical distribution law
Longitudinal velocity of ultrasound in aluminium	6 363 m/s	[6 313 m/s; 6 500 m/s]	Normal
Defect length along x axis	2.625 mm	[0.25 mm; 5 mm]	Constant/ Char. value
Defect depth position in adhesive	1.72 mm	[1.61 mm; 1.82 mm]	Uniform
Distance between sample surface and transducer	44.03 mm	[43.5 mm; 44.03 mm]	Uniform
Thickness of aluminium	1.61 mm	[1.60 mm; 1.61 mm]	Normal
Incidence angle	0°	[-6°; 0°]	Uniform

Determination of Influential Factors: Sensitivity Analysis

- Metamodel computation

Uncertain parameters	Sensitivity, indices of Sobol	Proportion value, %
Longitudinal wave velocity	0.04	0.03
Defect depth	3.53	2.95
Water path (distance between transducer and surface)	46.90	39.18
Thickness of aluminium	0.03	0.02
Incidence angle	69.21	57.82

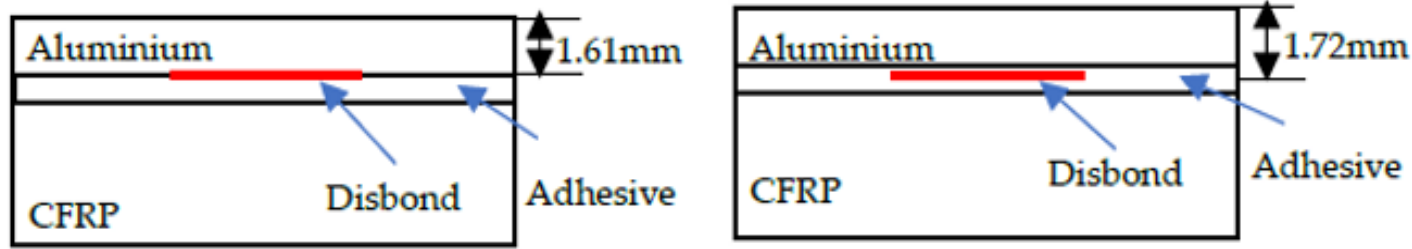




Amplitude of multiple reflections	Aluminium-disbond	Adhesive-disbond	Adhesive-GFRP
A_1	-0.2915	-0.1451	0.0468
A_2	-0.2424	0.1020	0.0106
A_3	-0.2016	-0.0717	0.0024
A_4	-0.1676	-0.0504	0.00054

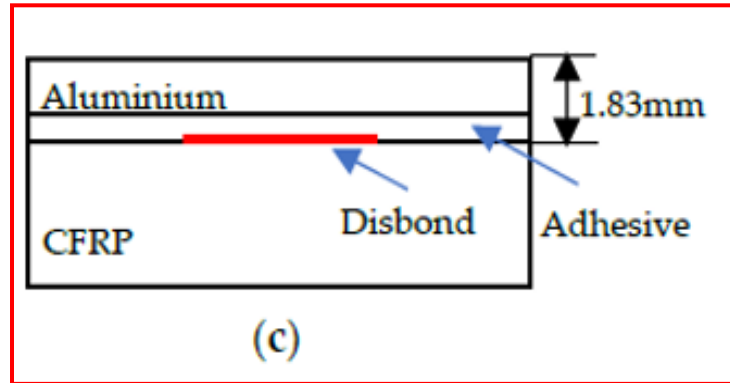
Numerical Evaluations

Inspection performed from the metal side of the sample

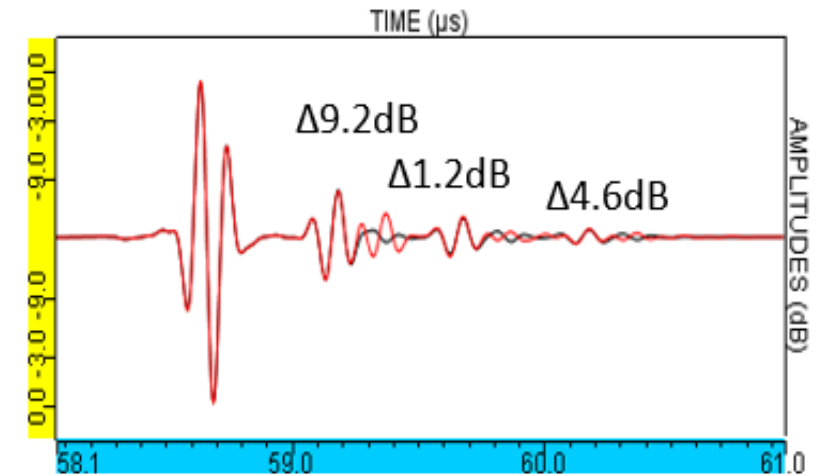
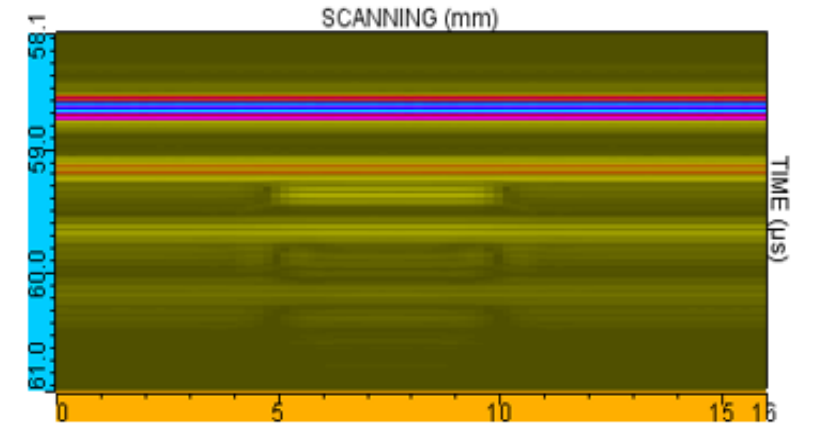


(a)

(b)

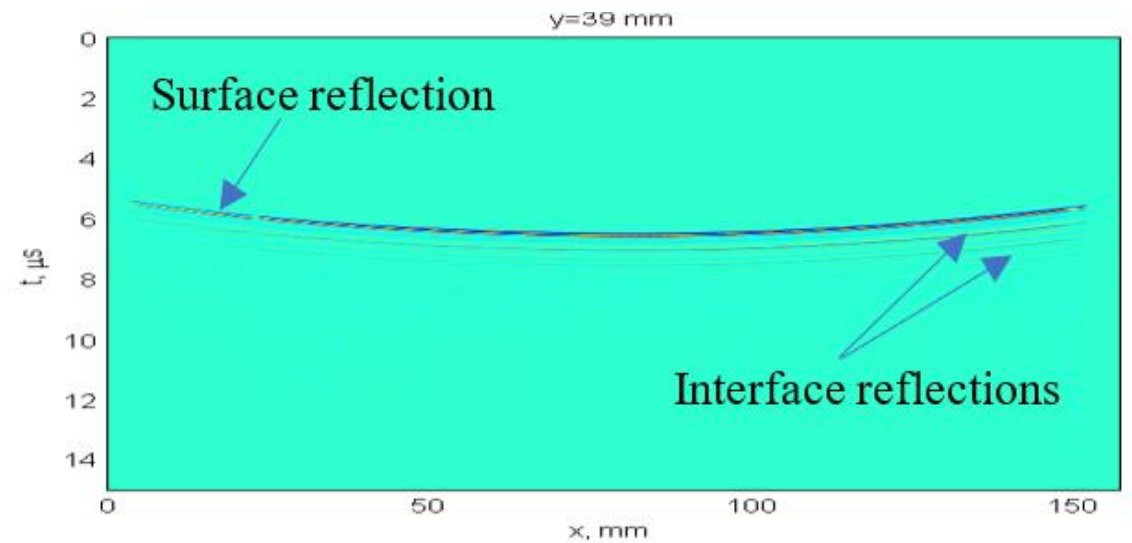
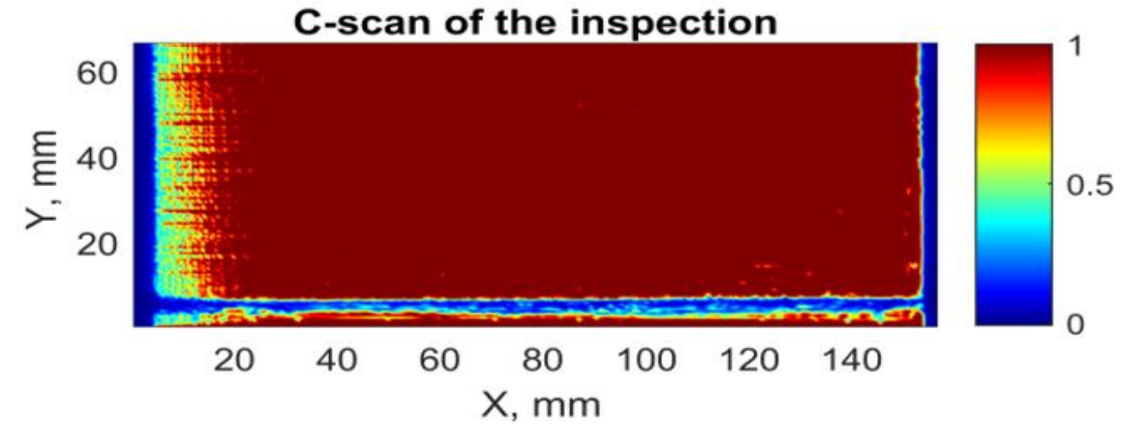
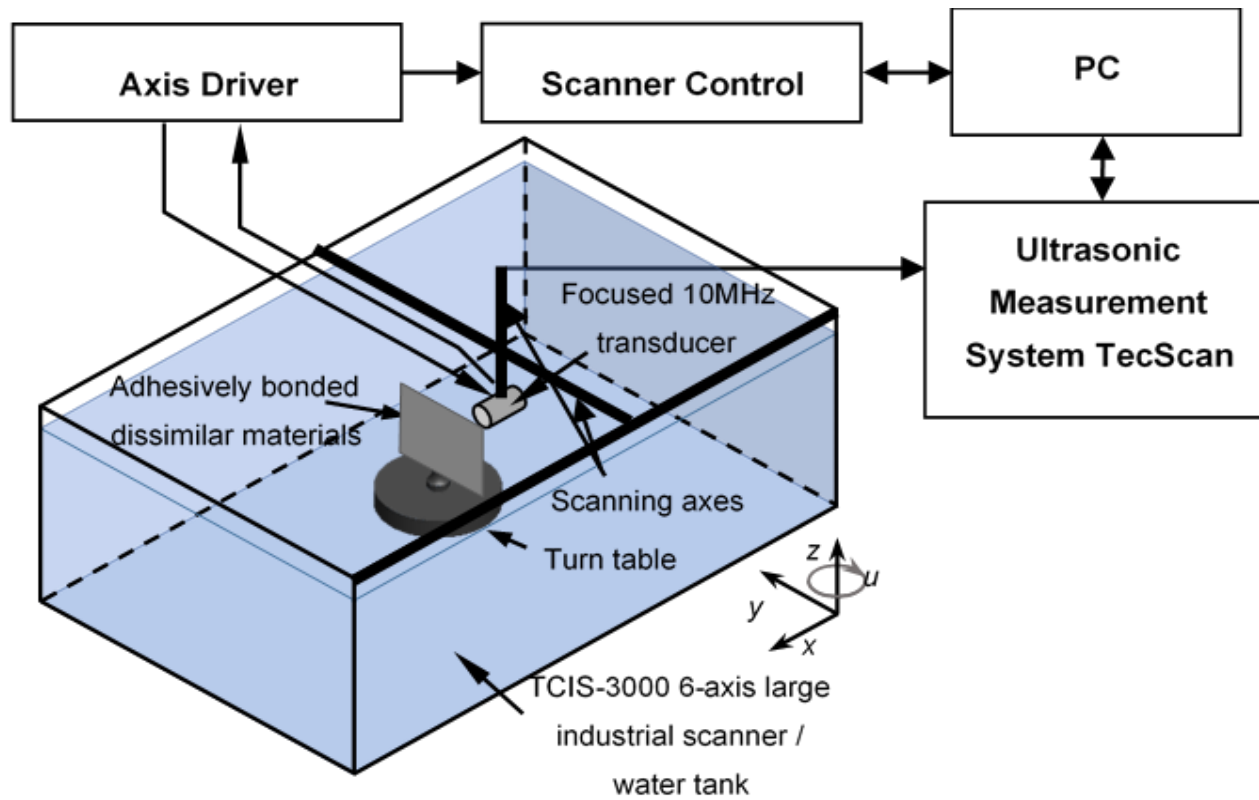


(c)

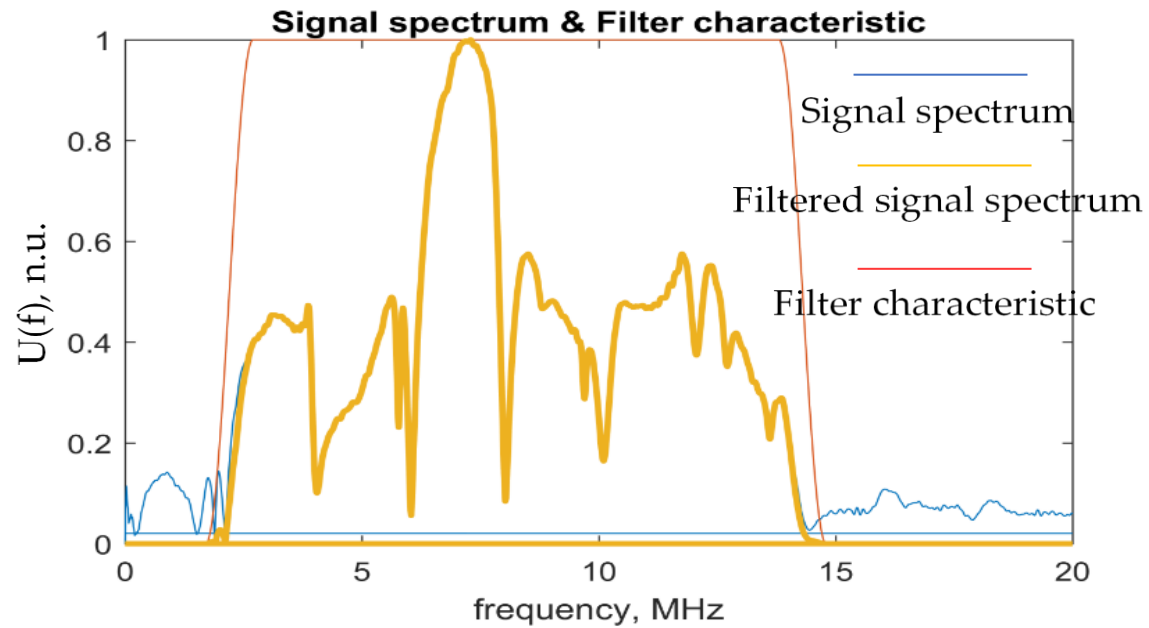


c

Experimental Investigation



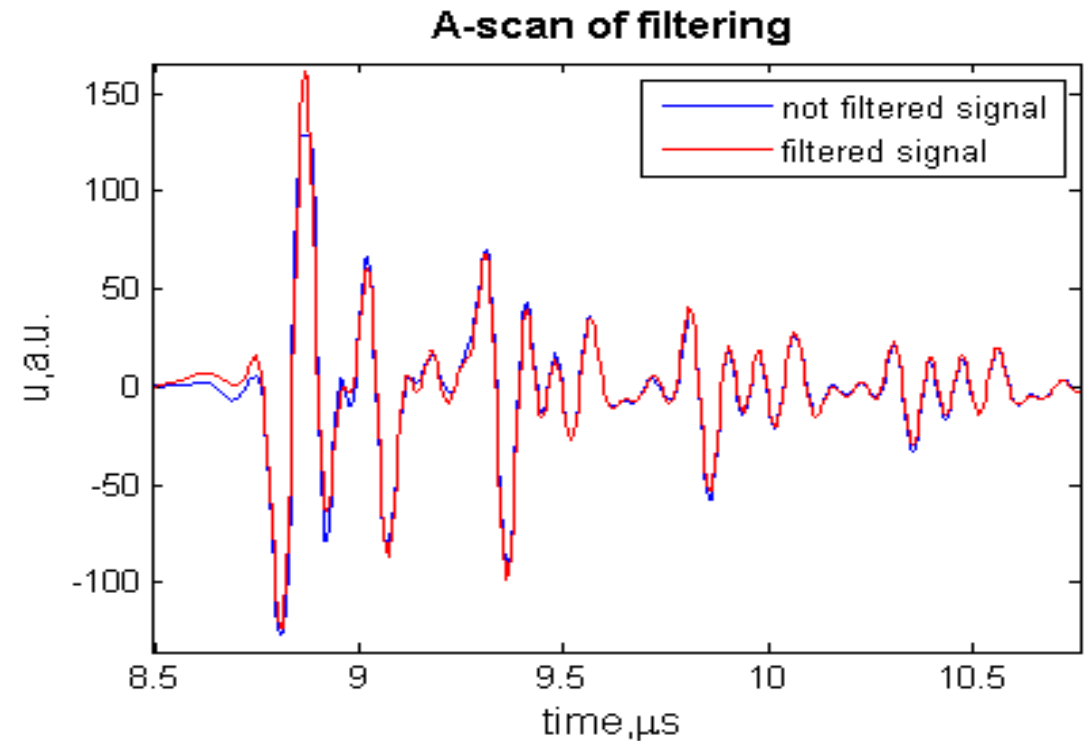
Development of Post-processing Algorithm: Signal Filtering & Time Alignment



$$U(f) = \text{FT}[u(t)];$$

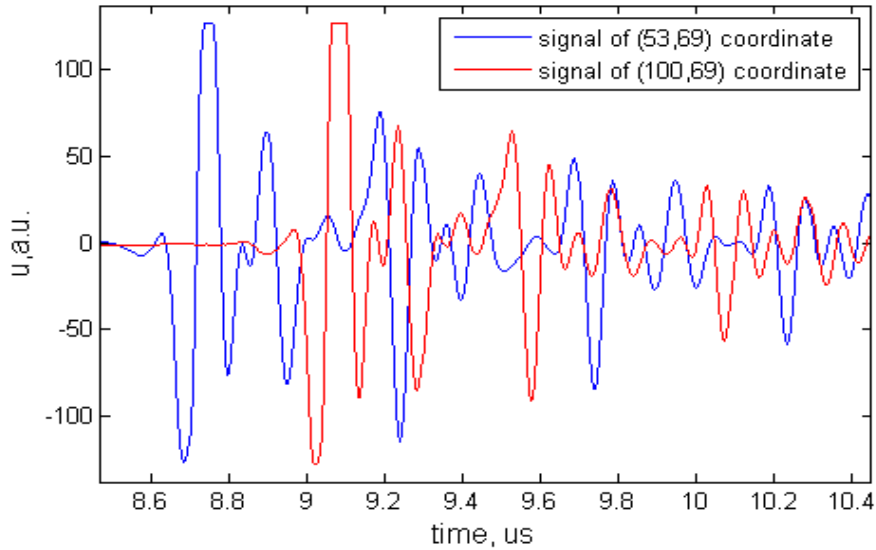
$$U_F(f) = U(f) \cdot H(f);$$

$$u_F(t) = \text{Re}(\text{FT}^{-1}[U_F(f)]);$$



Development of Post-processing Algorithm: Signal Filtering & Time Alignment

A-scan before time alignment

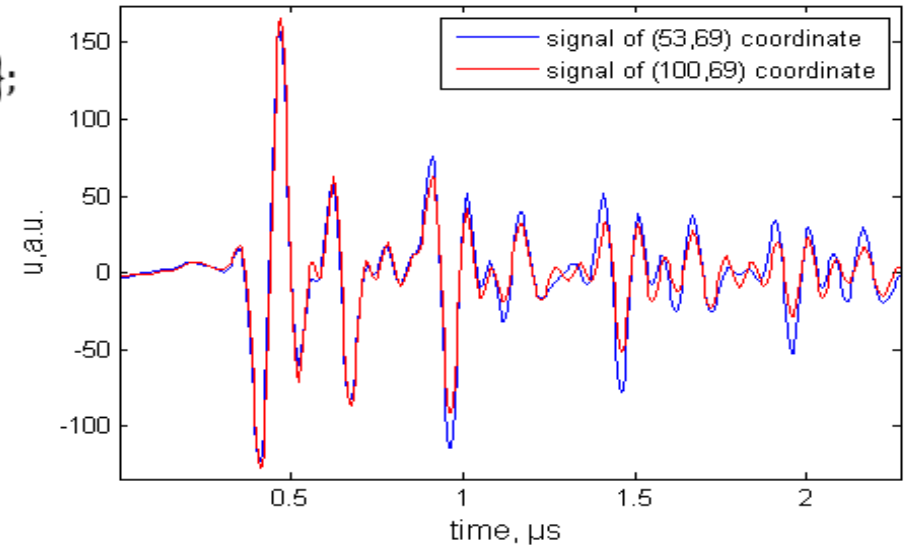


$$t_{n_1,k} = \min\{\arg[u_k(t_{n_1}) > U_{th}]\};$$

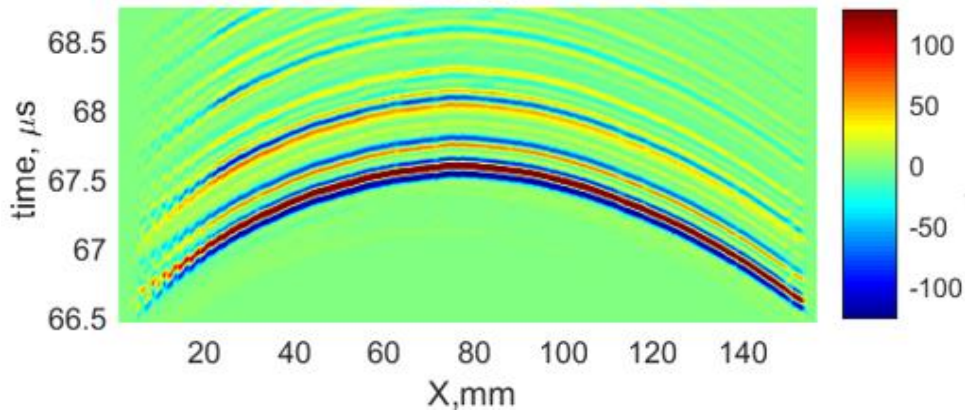
$$t_{0,k} = \min\{\arg [u_k(t_n) = 0]\};$$

$$u'_k(t_n) = u_k(t_n + t_{0,k});$$

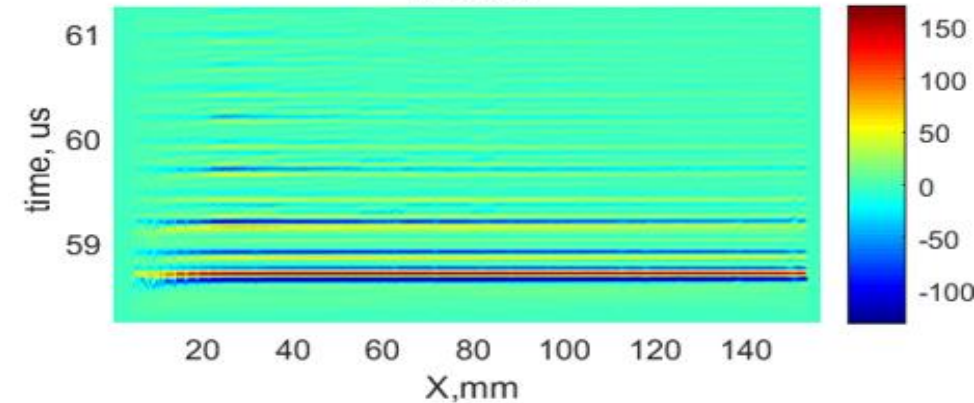
A-scan of aligned time reflections



B-scan



B-scan



Task 2: Determination & extraction of UT features capable to increase probability of defect detection

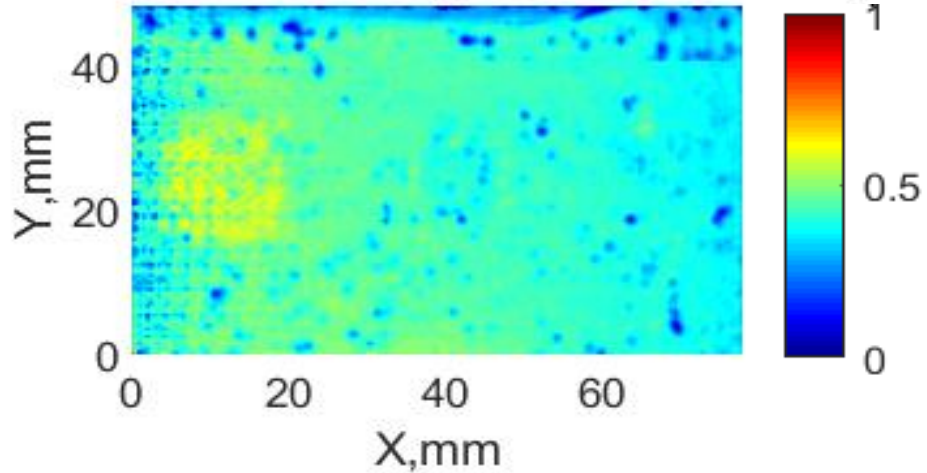
Determination & Extraction of UT Features

Extracted features:

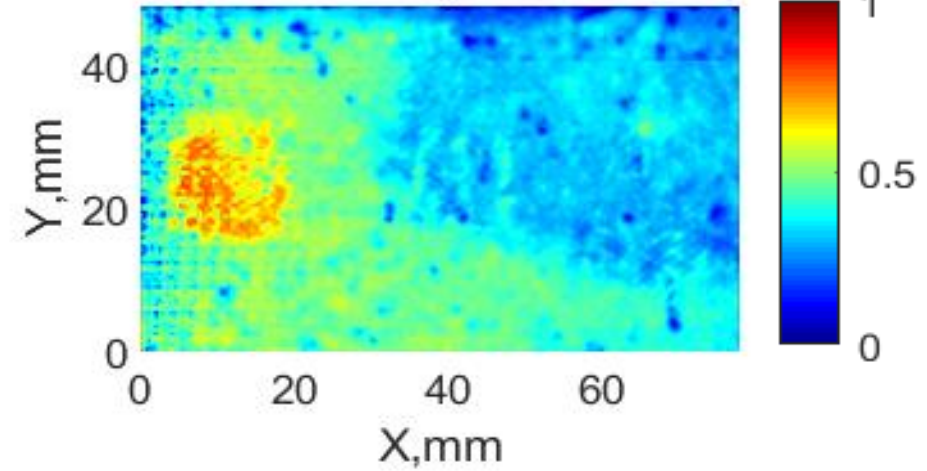
- Peak-to-peak amplitude at multiple interface reflections and at calculated time intervals where the maximum amplitude change occurs;
- Attenuation;
- Frequency domain maximum amplitude;
- Absolute energy;
- Frequency value at the maximum amplitude;
- Ratio coefficient of peak-to-peak amplitudes at certain time intervals.

UT Feature: Peak-to-peak amplitude at multiple interface reflections

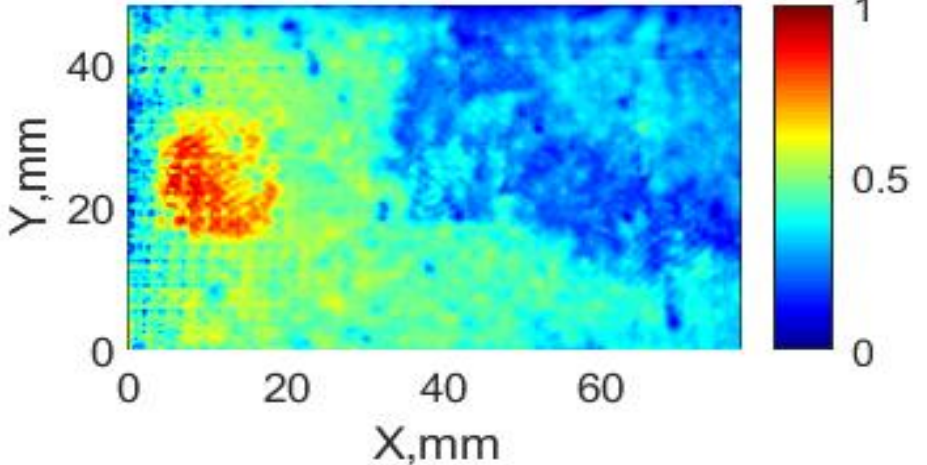
Cscan - Peak to Peak, Gate:59.08-59.58 μs



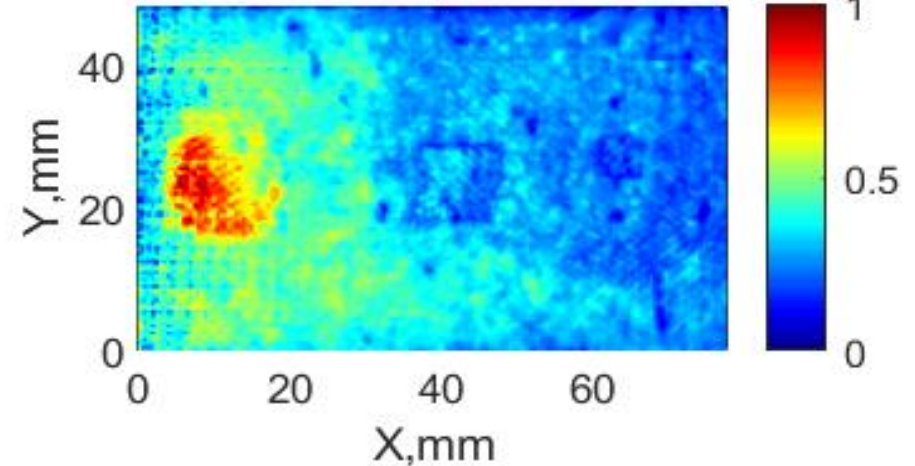
Cscan - Peak to Peak, Gate:59.58-60.07 μs



Cscan - Peak to Peak, Gate:60.07-60.57 μs



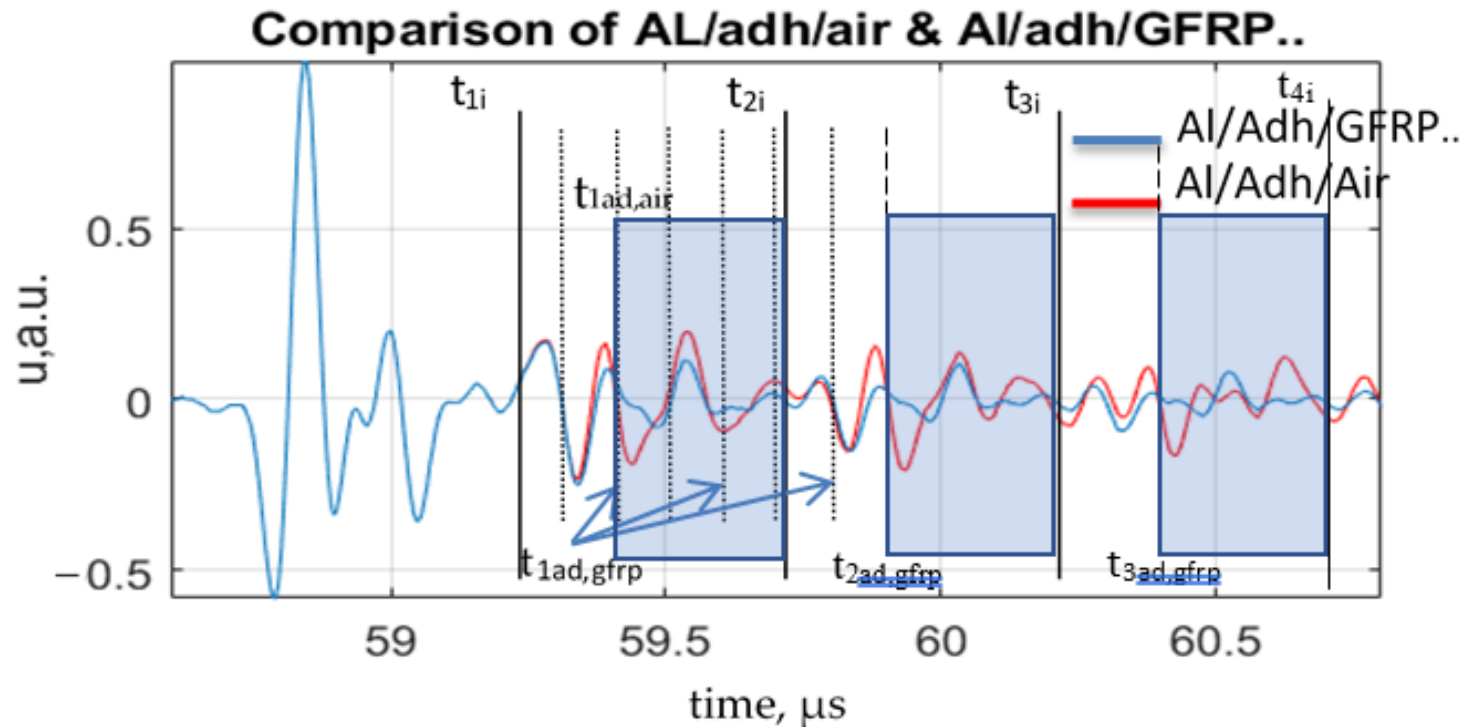
Cscan - Peak to Peak, Gate:60.57-61.06 μs



UT Feature: Peak-to-peak amplitude at calculated time intervals where the maximum amplitude change occurs

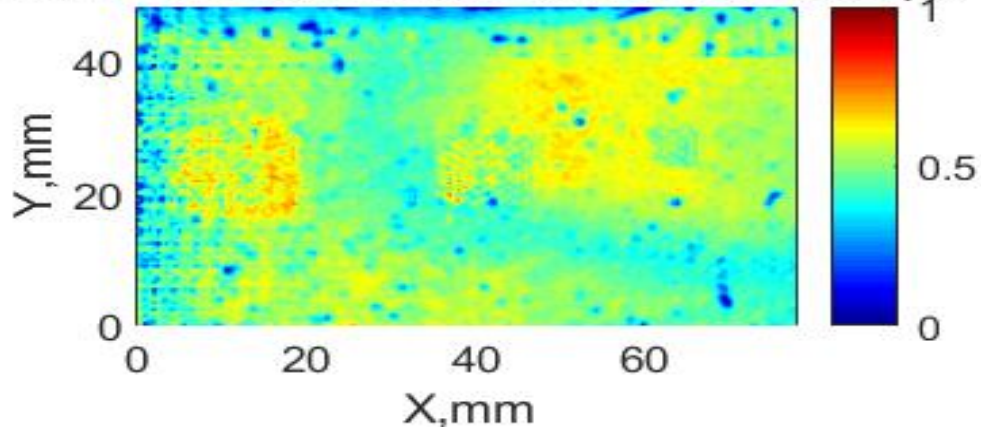
Models of perfect bonding (aluminium-adhesive-composite) and debonding in the middle of adhesive layer (aluminium-adhesive-disbond) were created and signals $u(t)$ modelled:

$$u(t) = y_{ref}(t) \otimes h(t);$$

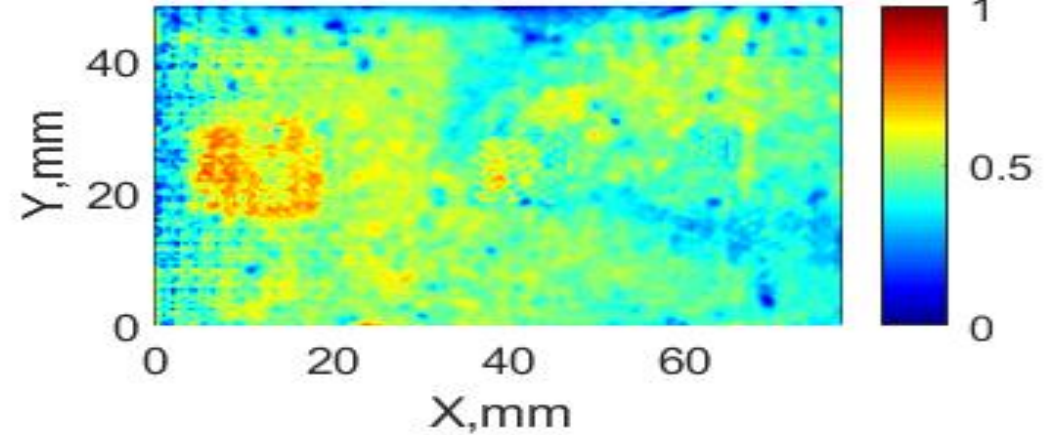


UT Feature: Peak-to-peak amplitude at calculated time intervals where the maximum amplitude change occurs

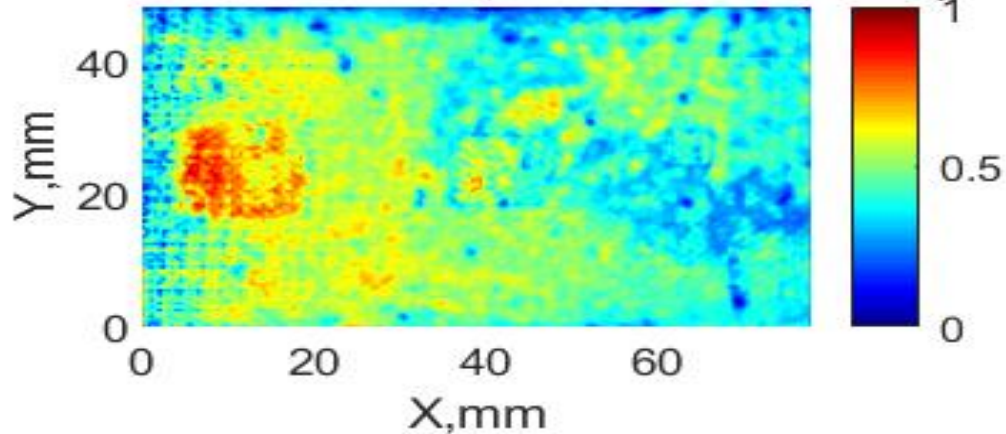
Cscan - Peak to Peak, Gate:59.27-59.58 μs



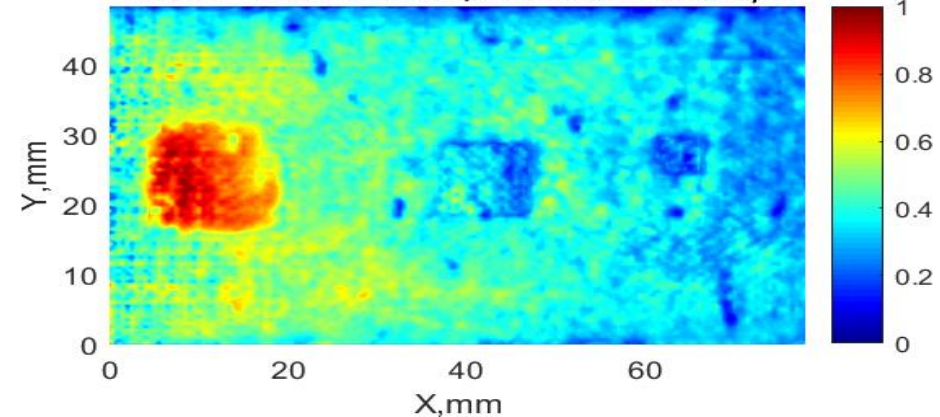
Cscan - Peak to Peak, Gate:59.77-60.07 μs



Cscan - Peak to Peak, Gate:60.26-60.57 μs

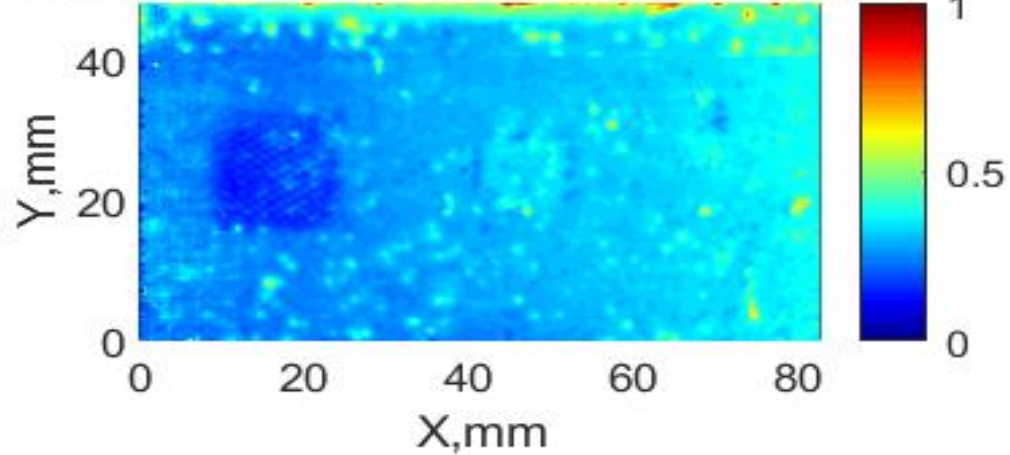


Cscan - Peak to Peak, Gate:60.76-61.06 μs

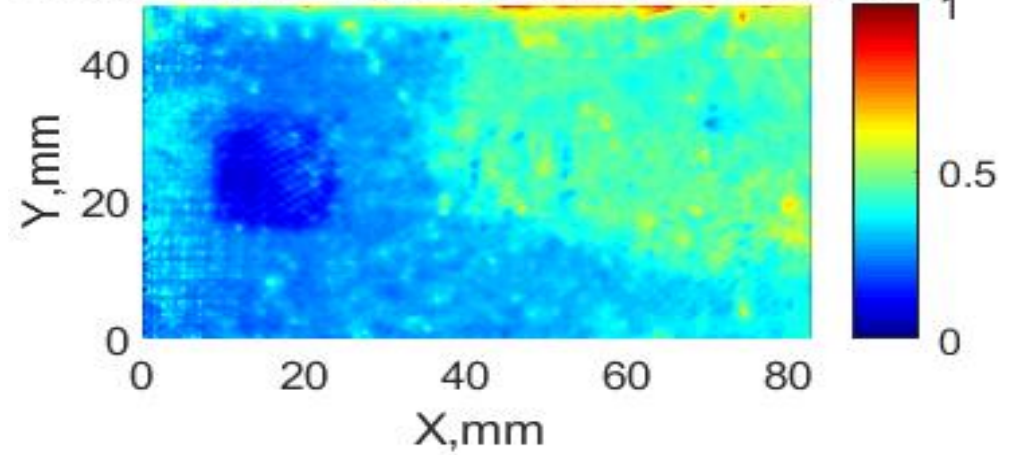


UT Feature: Attenuation

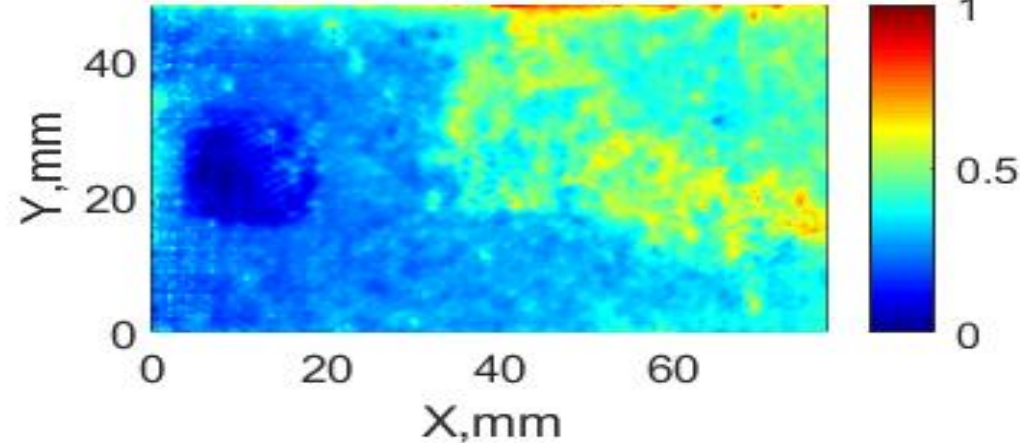
Cscan - Attenuation: surgace/interface1



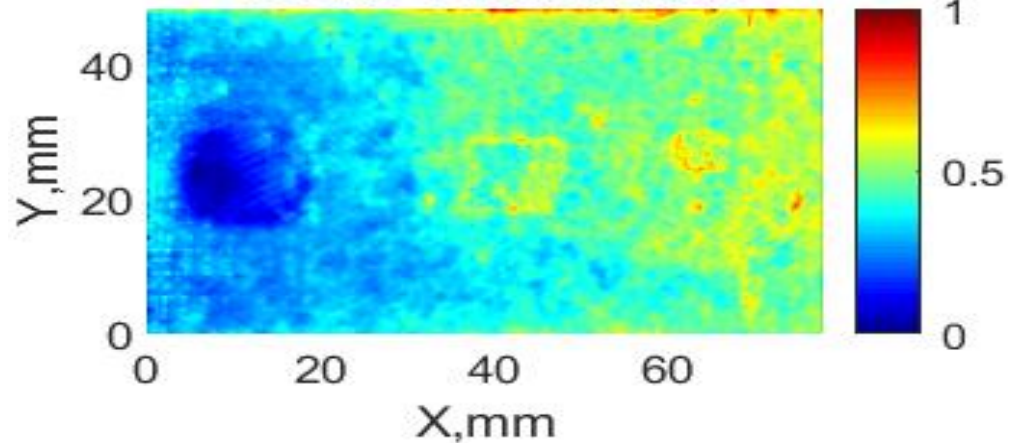
Cscan - Attenuation:surgace/interface2



Cscan - Attenuation:surgace/interface3

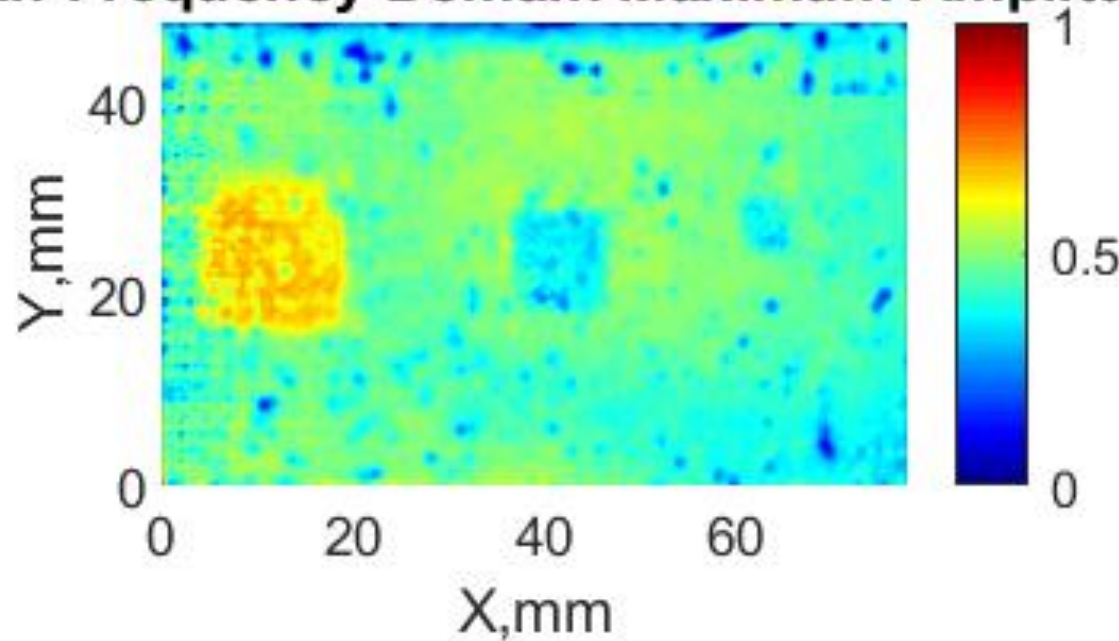


Cscan - Attenuation

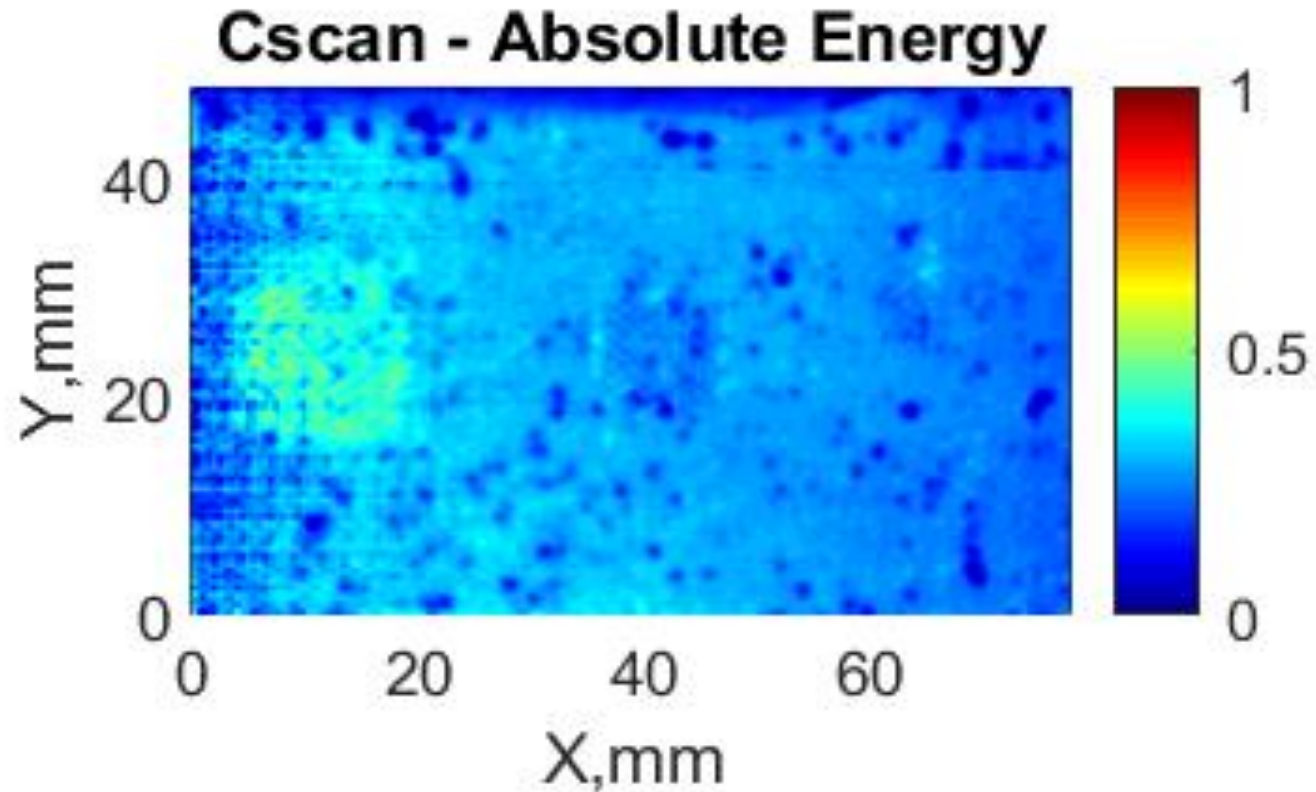


UT Feature: Frequency domain maximum amplitude

Cscan-Frequency Domain Maximum Amplitude

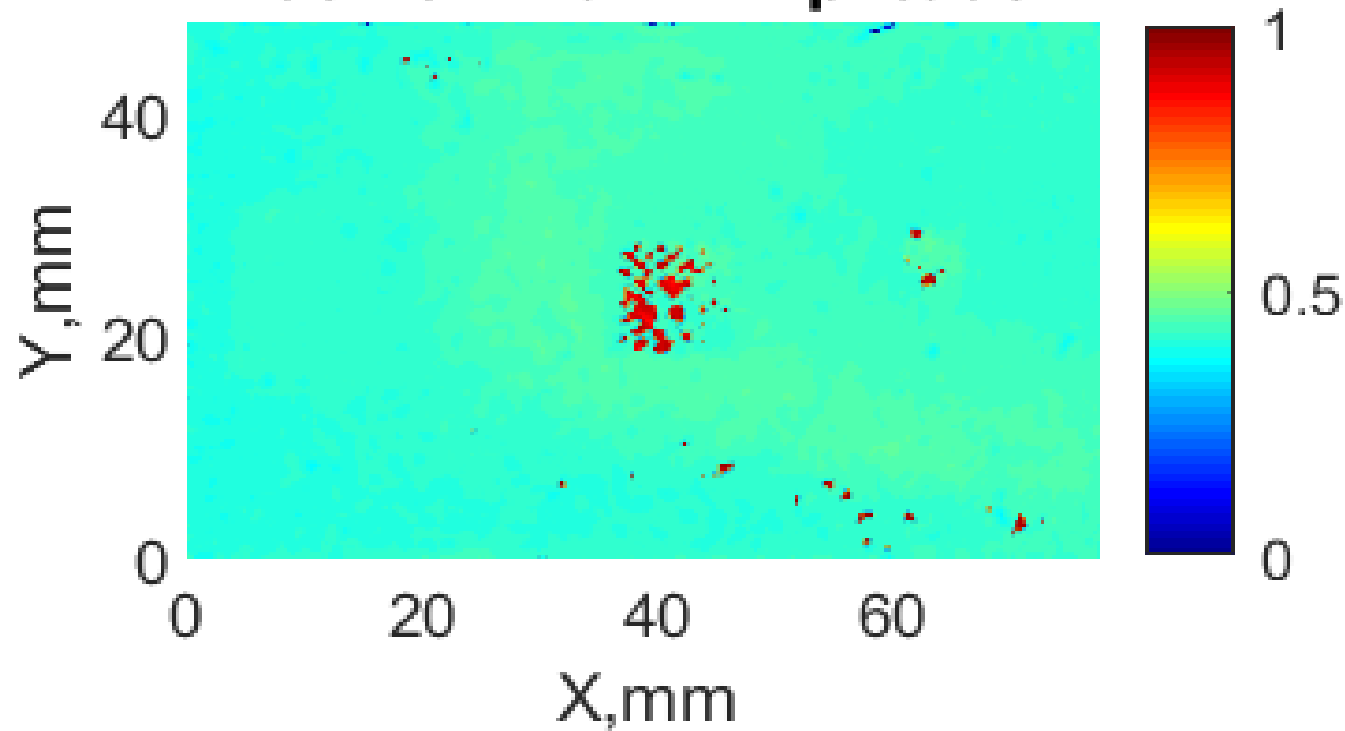


UT Feature: Absolute energy



UT Feature: Frequency value at the maximum amplitude

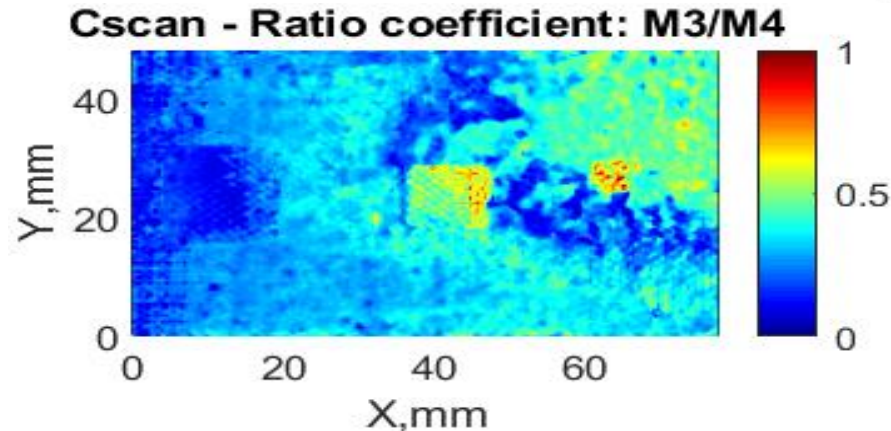
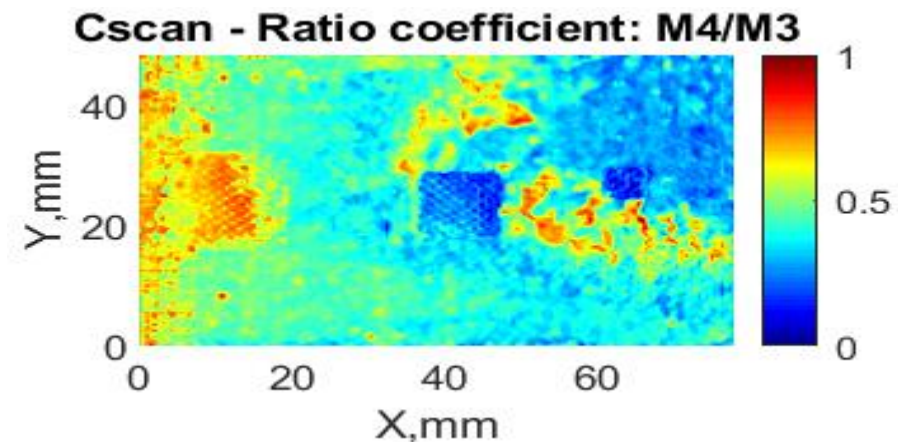
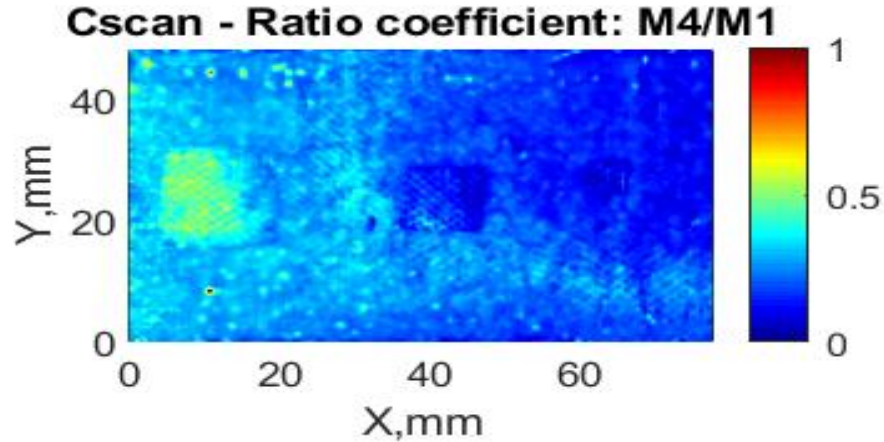
Cscan-Frequency Domain of Frequency value at Maximum Amplitude



UT Feature: Ratio coefficient of peak-to-peak amplitudes at certain time intervals

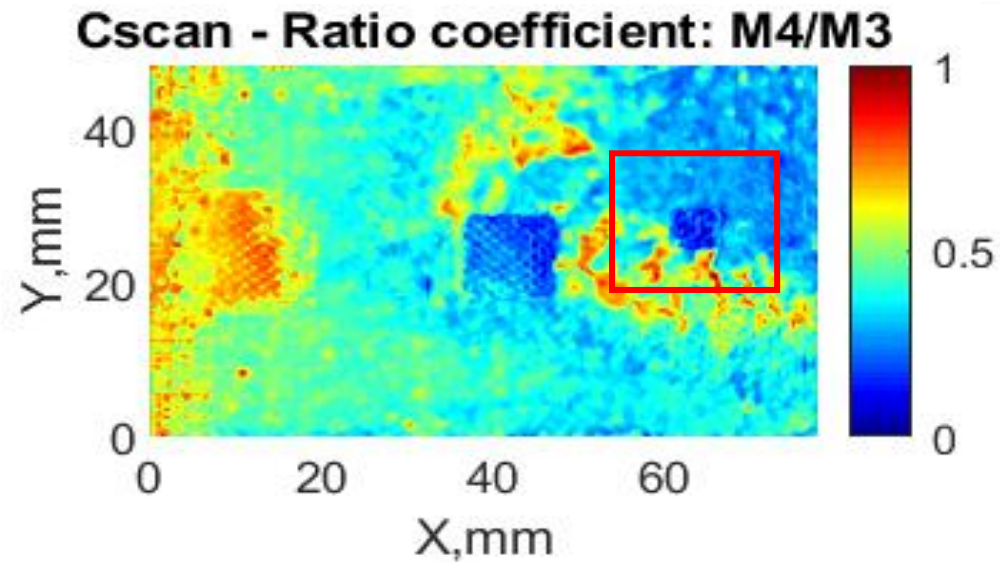
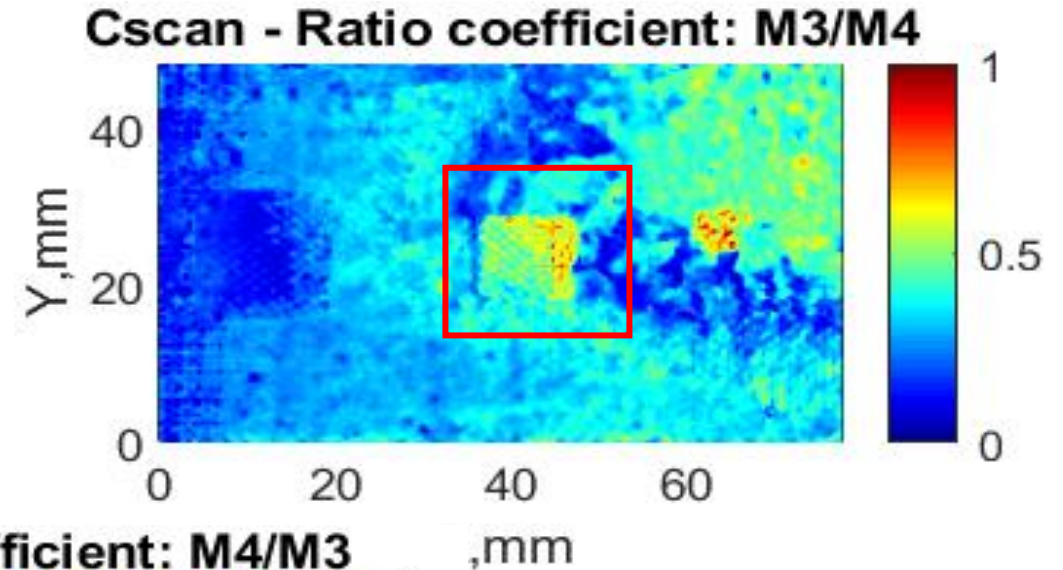
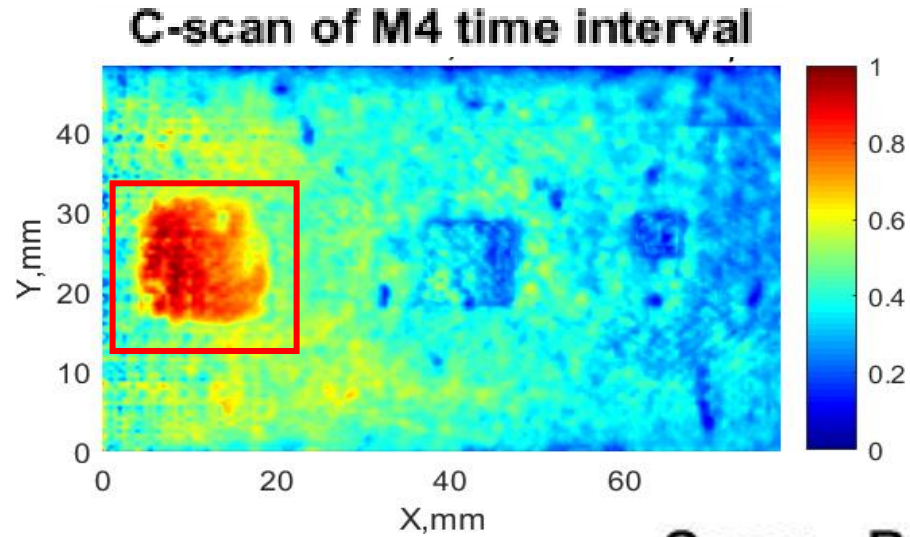
Ratio coefficients of peak-to-peak amplitudes calculation:

$$K_1 = \frac{M_n}{M_{n+1}};$$
$$K_2 = \frac{M_{n+1}}{M_n};$$



Task 3: Evaluation of extracted features performance using -6dB threshold sizing method

Performance Evaluation: Defect Sizing



Performance Evaluation: Defect Sizing

Interface reflection	Slice along	Big defect size, mm	Medium defect size, mm	Small defect size, mm
M4	X axis	16.5	3.4	2.05
M4/M1	X axis	9.8	-	-
M4/M3	X axis	11.6	11.5	4.9
M3/M4	X axis	13.6	10.3	3.8

Future Plans

- Data fusion of C-scans received from different extracted features;
- Development of post-processing technique including artificial intelligence for automatic analysis of UT data and elimination of influential factors.

Conclusion: Steps of UT Data Analysis

1. Investigation of fundamentals of wave-disbond interactions;
2. Quantitative evaluation to study wave propagation in the structure;
3. Qualitative evaluations to determine factors influencing defect detection;
4. Determination of UT features capable to increase evaluation performance and to be used in post-processing technique;
5. Development of post-processing algorithms to eliminate influential factors and extract UT features;
6. Verification and comparison of evaluation performance for extracted features;
7. Development of logical loops in processing algorithm to make it more automatized.